Electronic Acknowledgement Receipt				
EFS ID:	1372655			
Application Number:	10696006			
International Application Number:				
Confirmation Number:	7106			
Title of Invention:	Structure for reducing leakage currents and high contact resistance for embedded memory and method for making same			
First Named Inventor/Applicant Name:	Kuo-Chi Tu			
Correspondence Address:	Daniel R. McClure THOMAS, KAYDEN, HORSTEMEYER & RISLEY, LLP. 100 Galleria Parkway Suite 1750 Atlanta GA 30339 US 770-933-9500			
Filer:	Daniel R. McClure			
Filer Authorized By:				
Attorney Docket Number:	TS02-1033			
Receipt Date:	13-DEC-2006			
Filing Date:	29-OCT-2003			
Time Stamp:	17:17:00			
Application Type:	Utility			
Payment information:				
Submitted with Payment	no			

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Amendment - After Non-Final Rejection	00459873.pdf	138714	no	8
Warnings:					

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

Total Files Size (in bytes):

138714

New Applications Under 35 U.S.C. 111

Information:

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.